

--	--	--	--	--	--	--	--	--	--



P.E.S. College of Engineering, Mandya - 571 401

(An Autonomous Institution affiliated to VTU, Belagavi)

Second Semester, M. Tech - VLSI Design and Embedded System (MECE)

Semester End Examination; May/June - 2018

Low Power VLSI Design

Time: 3 hrs

Max. Marks: 100

Note: Answer FIVE full questions, selecting ONE full question from each unit.

UNIT - I

- 1 a. Explain the static and dynamic power dissipation in CMOS circuits. 8
- b. Briefly discuss voltage, physical capacitance and activity factor in the power optimization process. 8
- c. Mention the four principal in low power. 4
- 2 a. Briefly explain the following in VLSI Design : 10
- i) Dynamic dissipation in CMOS ii) Transistor sizing and optimal gate oxide thickness
- b. Discuss the impact of technology scaling and innovation trends for low power devices. 10

UNIT - II

- 3 a. Mention the types of Adders. With neat diagram, explain Ripple Carry Adder. 10
- b. Describing the working of the current mode adders. 10
- 4 a. Explain the principal of Multiplier. Mention its advantage and disadvantage. 6
- b. With neat diagram, explain 8-bit Wallace Tree Multiplier. 8
- c. Draw the neat diagram of 4 x 4 unsigned Braun Tree Multiplier. 6

UNIT - III

- 5 a. Explain the source of power dissipation in DRAM. 10
- b. Discuss low power SRAM circuit techniques. 10
- 6 a. Explain state and dynamic flip-flops with example. 10
- b. In detail, explain the importance of CMOS low power cell library for digital design. 10

UNIT - IV

- 7 a. Discuss the new materials for wires and dielectrics. 10
- b. Discuss the following in low power VLSI design : 10
- i) Interconnection delay ii) Crosstalk
- 8 a. Briefly explain power and performance management in low power systems. 10
- b. Write short notes on : i) Guarded Evaluation ii) Glitch Reduction by Pipelining. 10

UNIT - V

- 9 a. Discuss the design techniques for safety critical application. 10
- b. Write a note on low power subsystem design. 10
- 10 a. Explain the single driver versus distributed buffers. 10
- b. With the help of relevant block diagram, explain the chip and package code design of clock network. 10